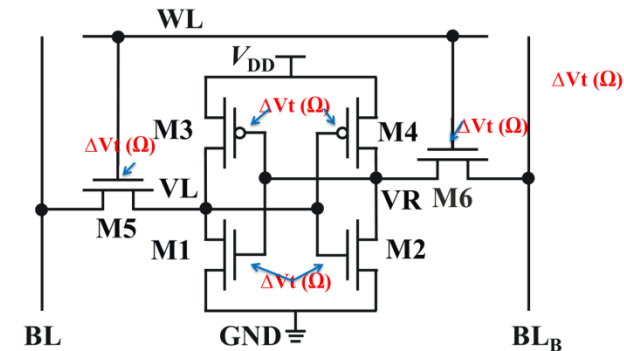
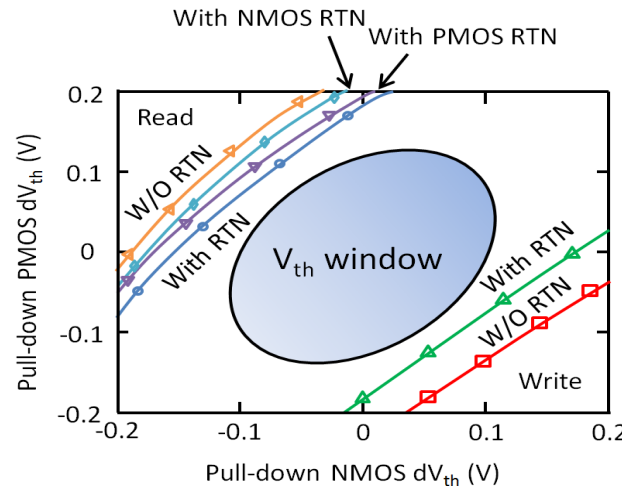
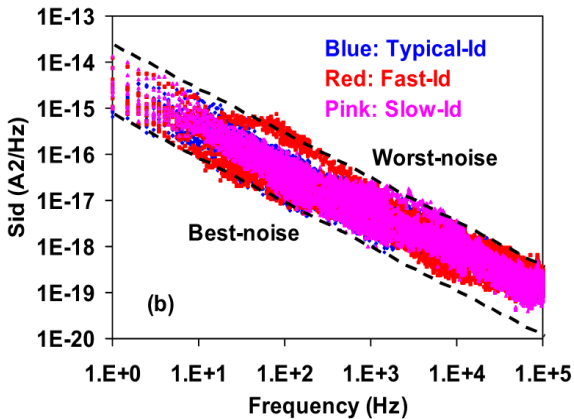


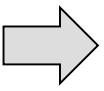
Platform Design Automation - The EDA Platform Company

Noise Characterization, Modeling and Its Impact on Highly Scaled Designs – from 0.1Hz to MMW

<http://www.platform-da.com>



Agenda



➤ Noise is a Source of Variability

Less Physics

➤ Noise Introduction and Its Impact on Designs

❖ RTN – SRAM

❖ 1/f – VCO

❖ Thermal – LNA & ADC

Design Perspectives

➤ PDA Noise: NC300A Introduction

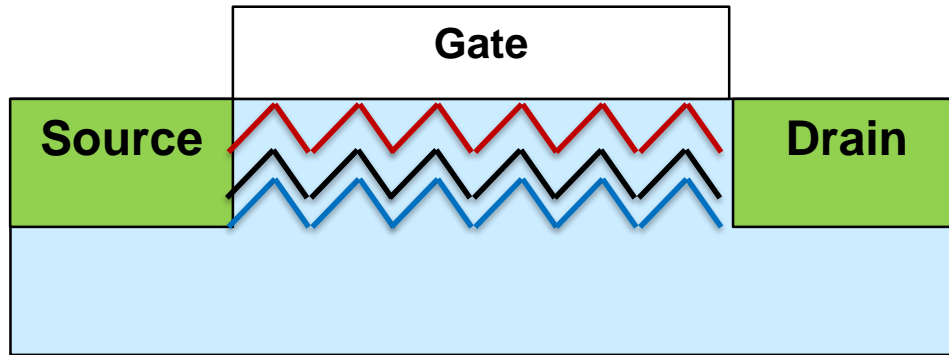
❖ Reveal Architect Fundamentals

❖ Product Advances

Measure/Simulate
Noise Accurately

➤ Conclusions

Source of Variabilities



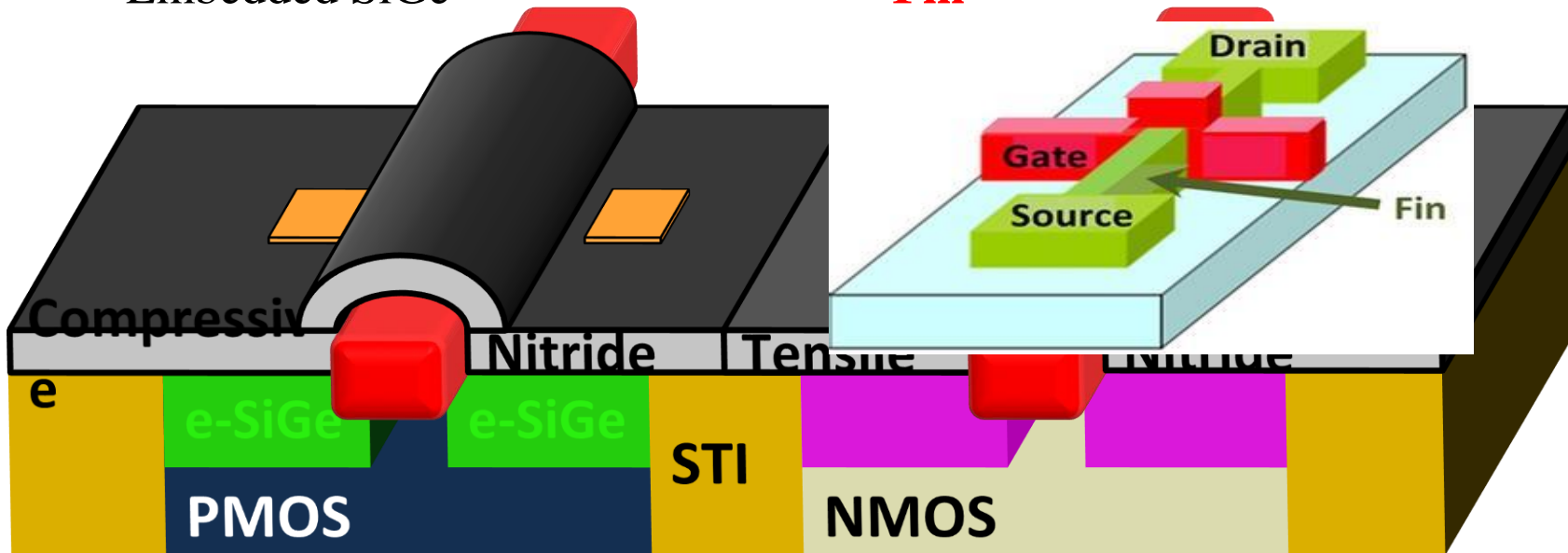
Mobility - **LDE**

Dopant – **RDF: Mismatch**

Traps/Defects – **NBTI, Noise**

- Shallow trench isolation
- Embedded SiGe

- Dual-stress nitride liner
- **Fin**

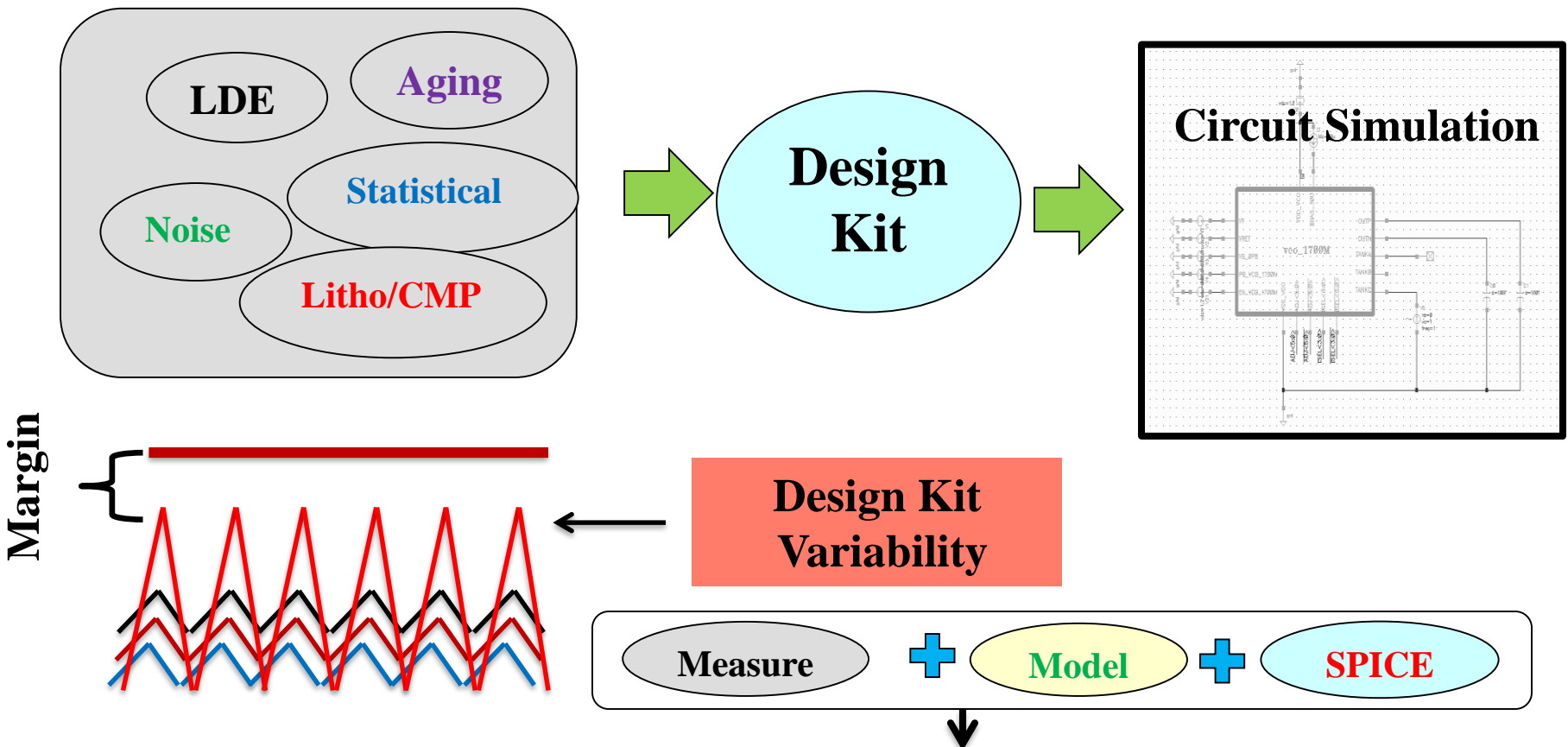


Source: Y.F. Li, et.al "A Complete and Automatic Advanced Model Verification Platform for 32nm Technology and Beyond"

Noise is a source of Variability

Variability in Design Kit vs. Design Margin

- The “Carrier” of Variability is the **Design Kit**
- “Human” variability may present a bigger challenge that limits **design margin**

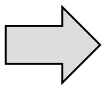


Goal: Enable Accurate Simulation of Variability including Noise!

Agenda

- Noise is a Source of Variability

Less Physics



- Noise Introduction and Its Impact on Designs

- ❖ RTN – SRAM

- ❖ 1/f – VCO

- ❖ Thermal - LNA

Design Perspectives

- PDA Noise:NC300A Introduction

- ❖ Reveal Architect Fundamentals

- ❖ Product Advances

- Conclusions

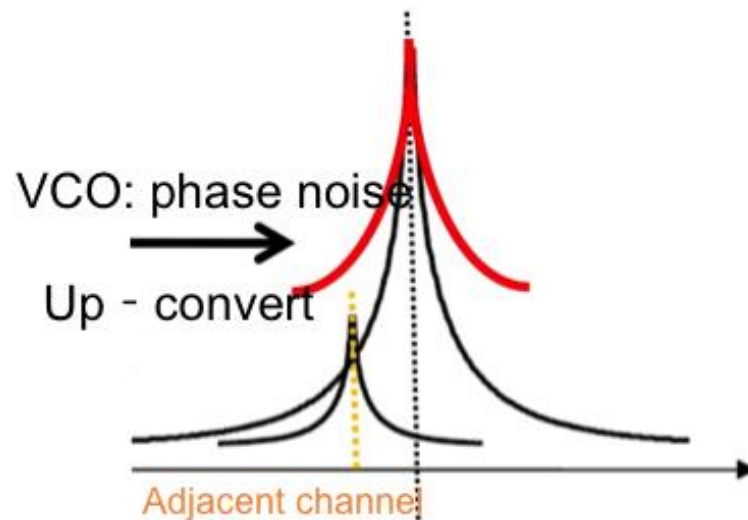
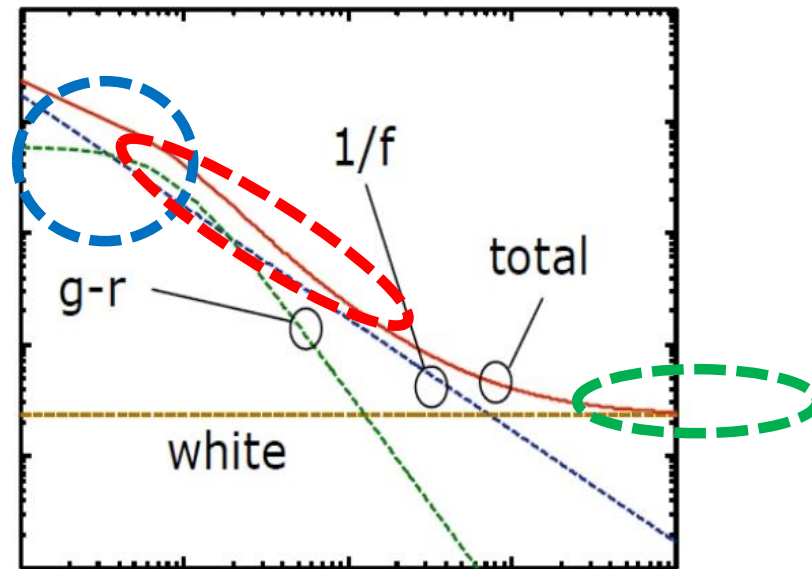
Measure/Simulate
Noise Accurately

Noise: Introduction

- G-R noise: trap/de-trap (**RTN**)
- **Flicker noise**: Trap distribution and mobility frustration
- Thermal Noise: **High frequency noise**

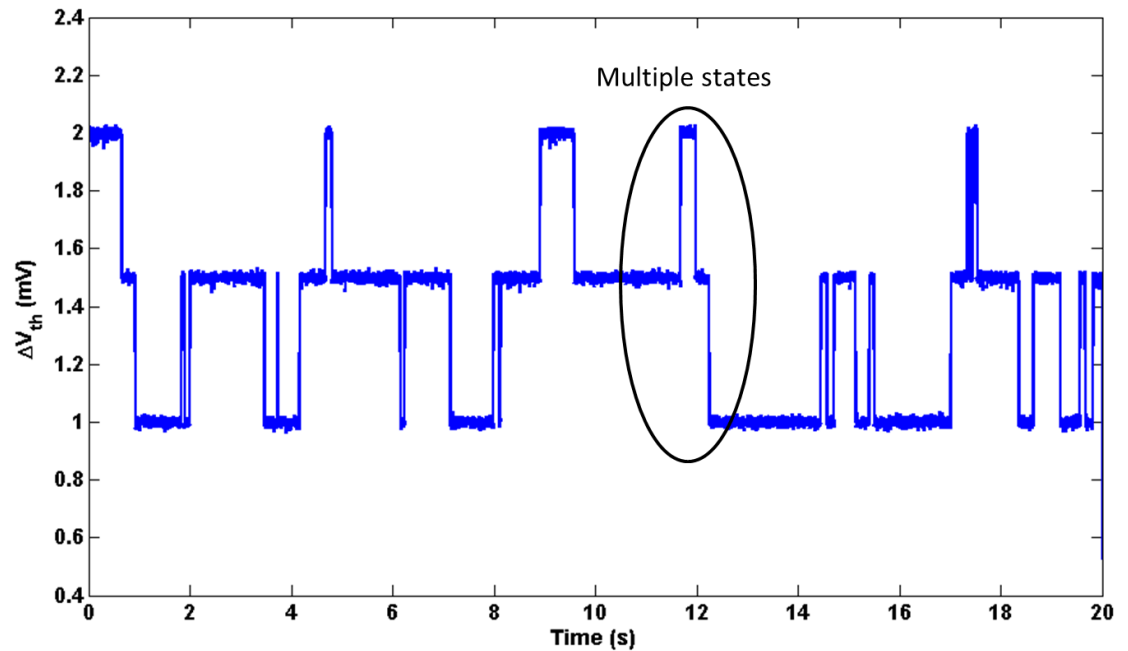
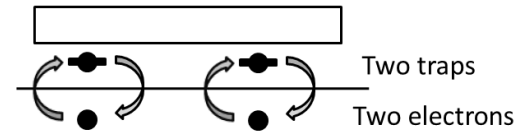
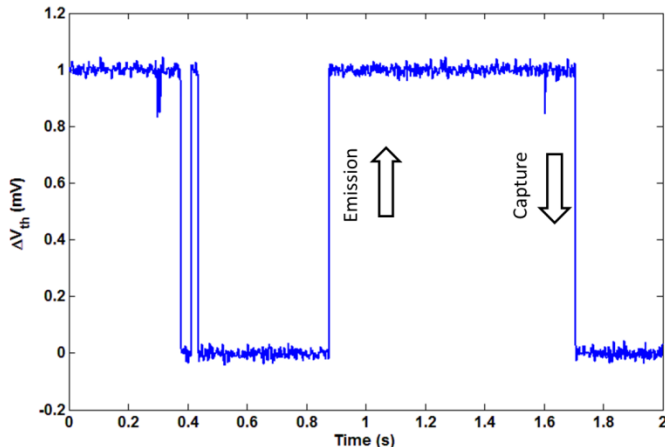
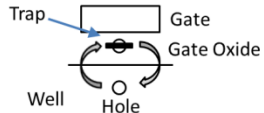
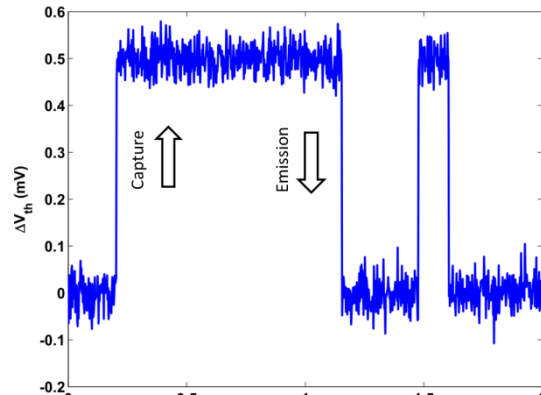
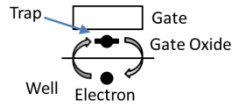
Focus

- **Why** it is required?
- Noise sensitive **circuits**.
- Modeling and implementation in circuit **simulation**.
- Characterization techniques



Low Frequency Noise - RTN

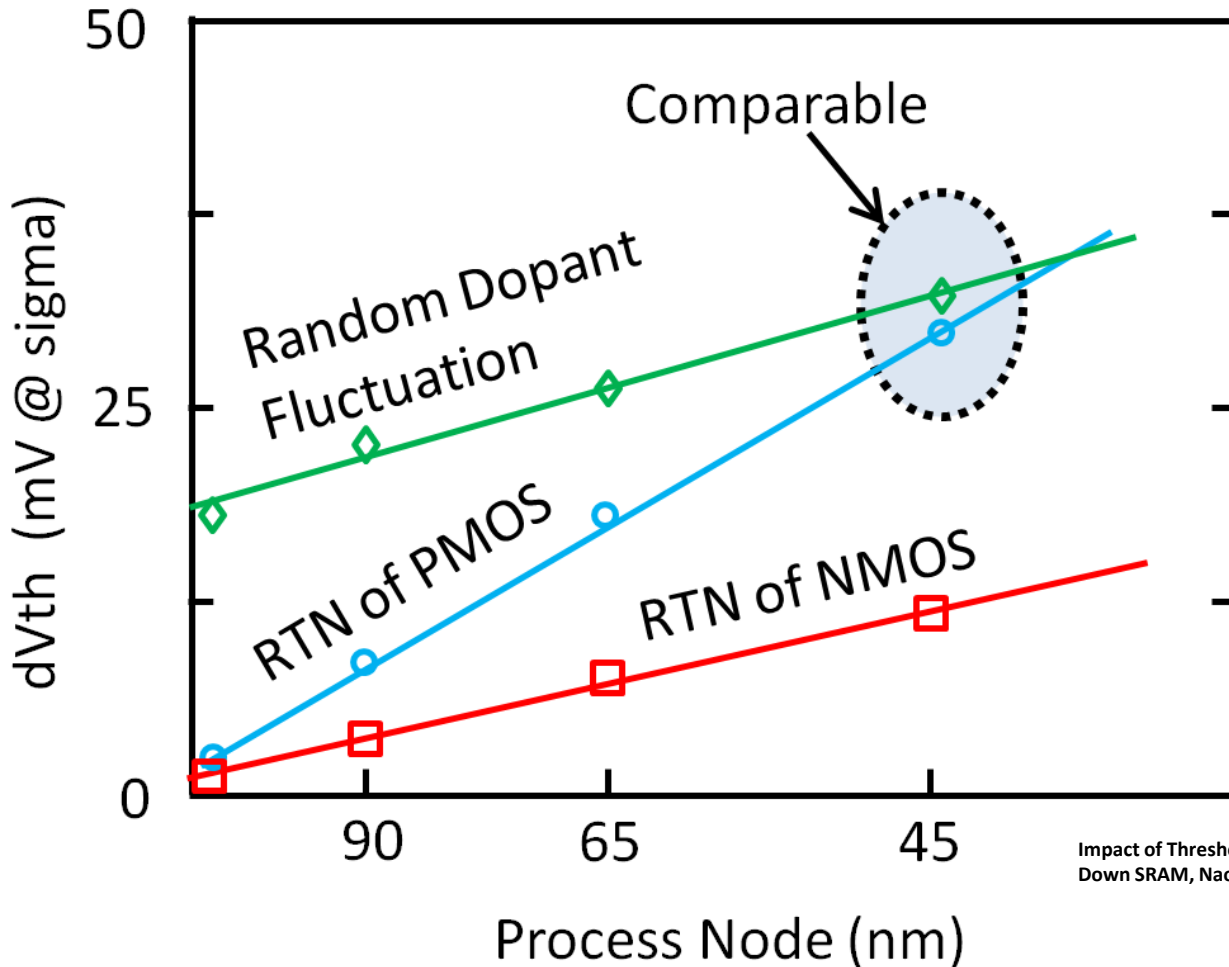
➤ Random Telegraph Noise: Trap/De-trap



Symptoms: Vibrations in V_{th}

Why Suddenly RTN is Important?

- ΔV_{th} due to **RTN** is comparable with ΔV_{th} caused by **RDF** for advanced process



RTN

$$\Delta V_{th} = \frac{q}{L_{eff} W_{eff} C_{ox}}$$

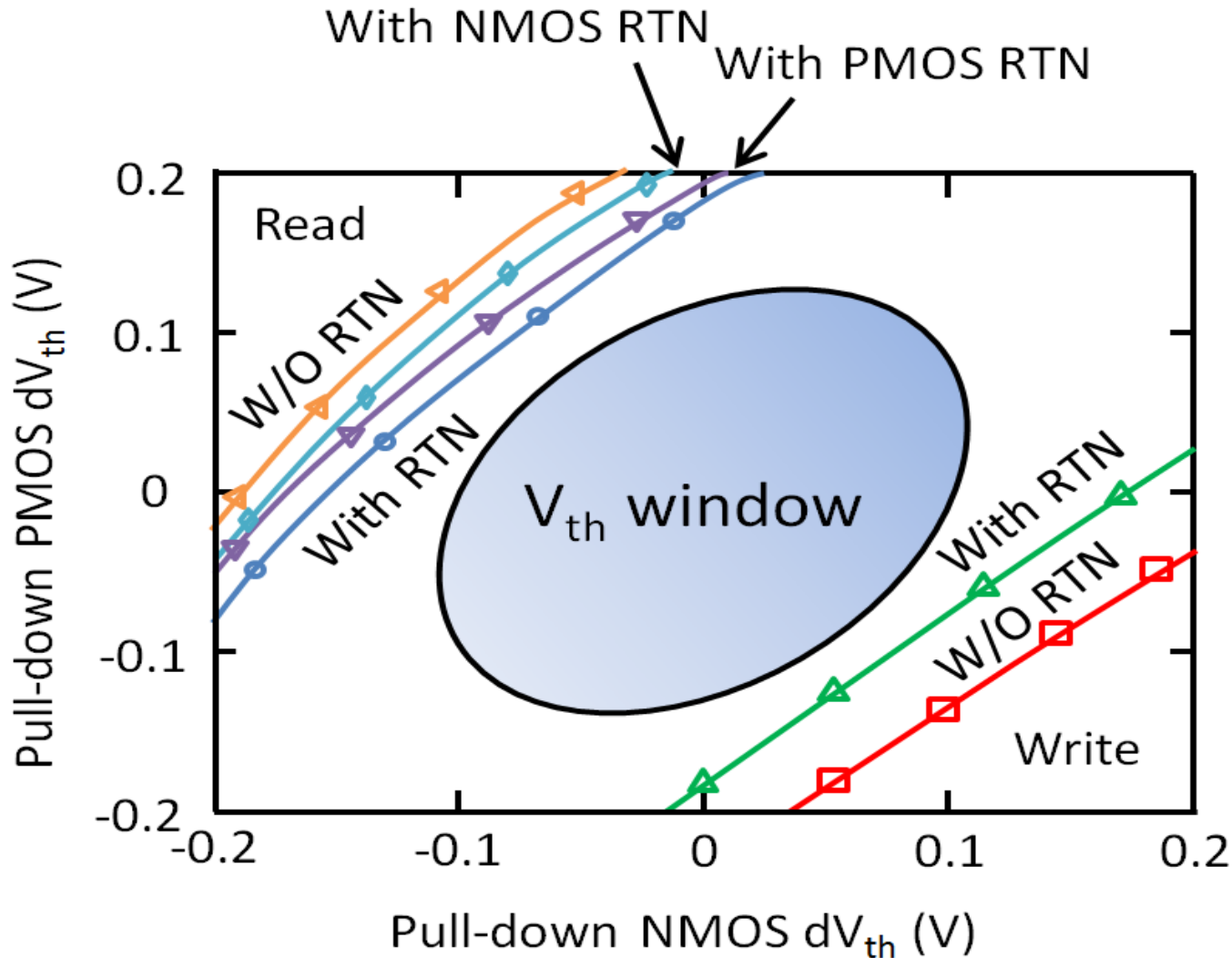
RDF

$$\Delta V_{th} = \frac{AV_{th0}}{\sqrt{LW}}$$

Impact of Threshold Voltage Fluctuation Due to Random Telegraph Noise on Scaled Down SRAM, Naoki Tega, IRPS 2008

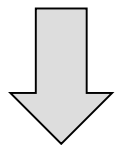
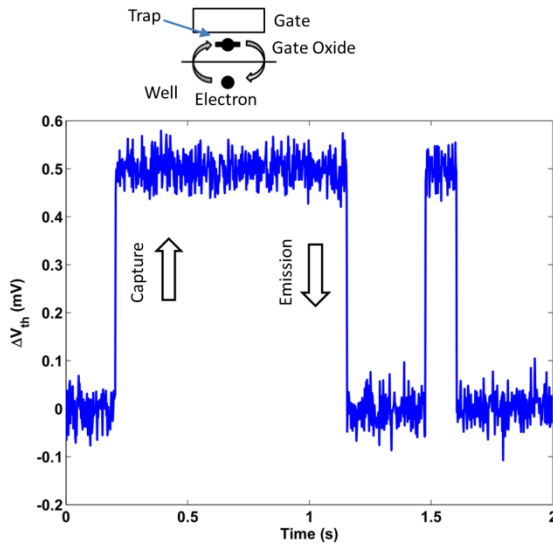
Analyze RTN in SRAM – Method 1: Yield

- Treat **RTN** caused ΔV_{th} same as ΔV_{th} caused by **RDF**

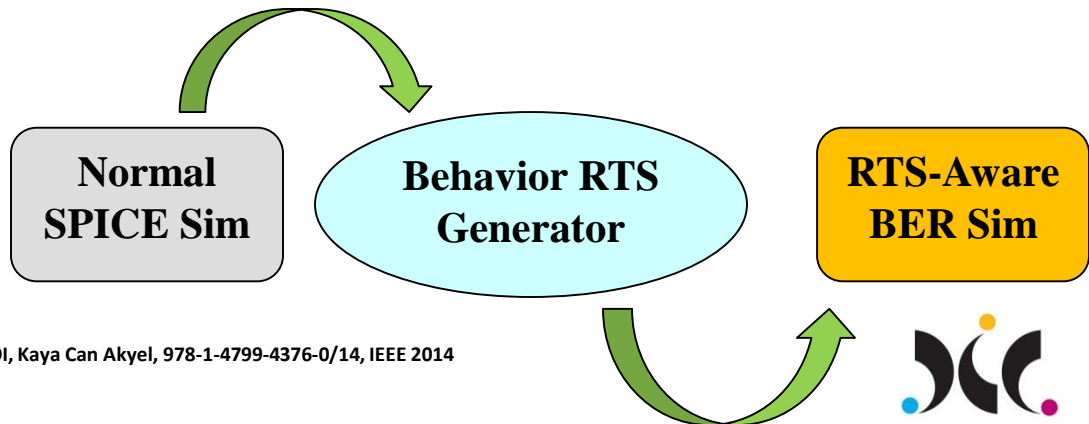
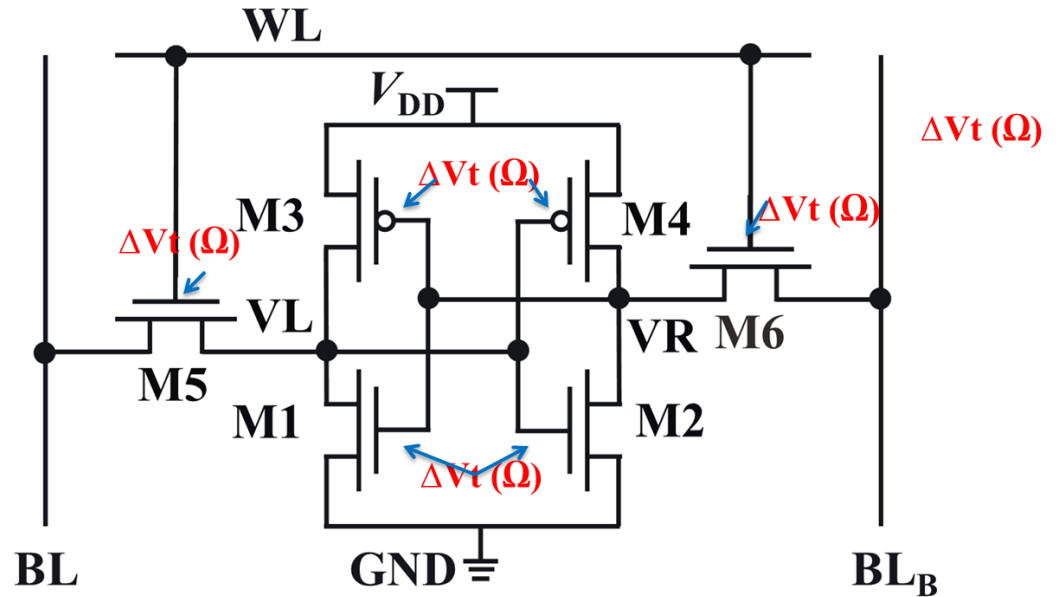


Analyze RTN in SRAM – Method 2: BER

- Implement RNT caused V_{th} variation into **SPICE** as a voltage source and simulate **BER**



Behavior description of RTN V_t
 $\Delta V_{th} = f(V, t, \dots)$



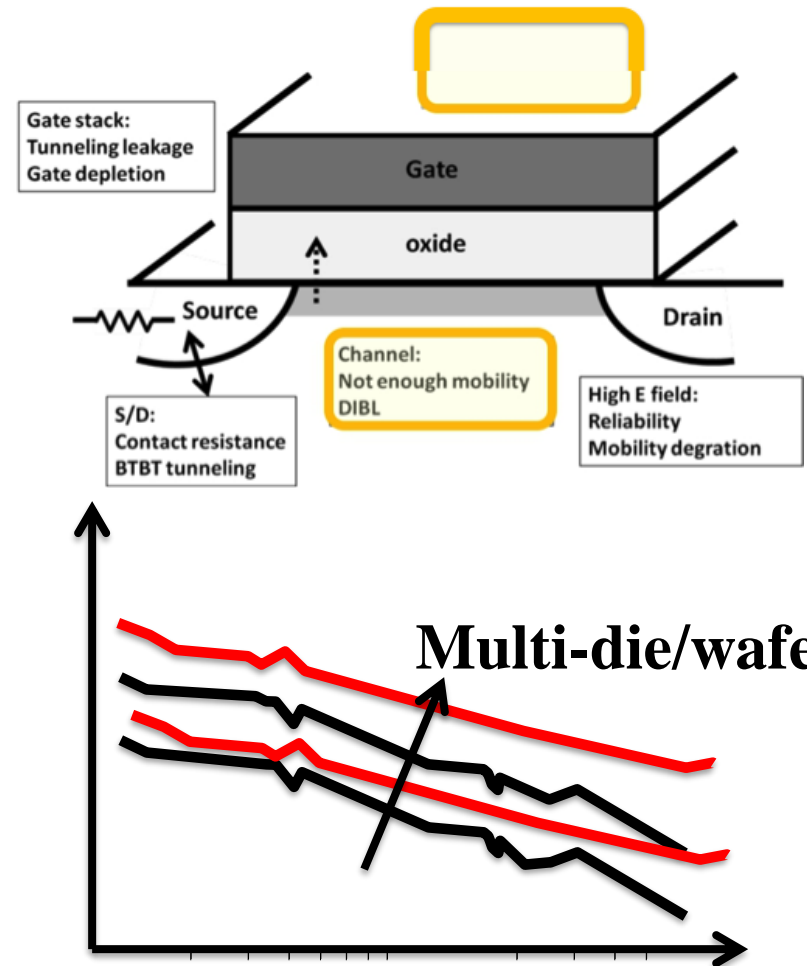
Impact of Random Telegraph Signals on 6T High-Density SRAM in 28nm UTBB FD-SOI, Kaya Can Akcel, 978-1-4799-4376-0/14, IEEE 2014

RTN Summary

- Comparable to **RDF** at advanced process node
- Strong impact on small geometry devices
 - ❖ **SRAM**
- Measuring RTN is only **half-way** through, modeling implementation and circuit simulation are required to complete the task
 - ❖ **Yield based simulation** similar to that of RDF
 - ❖ **SPICE BER** simulation with behavior RTN model

Low Frequency Noise – 1/f

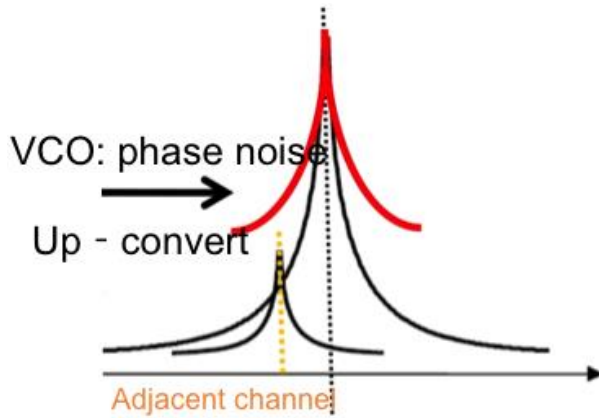
- Circuits are more sensitive to 1/f noise at advanced process nodes
 - ❖ Becomes a must-have SPEC by designers
- Variability of Noise scales with process variability
 - ❖ Needs to measure “Corner”
- Design requires accurate noise simulation
 - ❖ Requires accurate noise and its statistical modeling



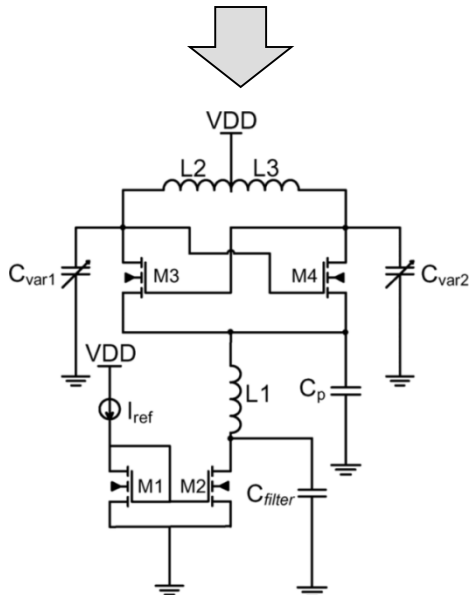
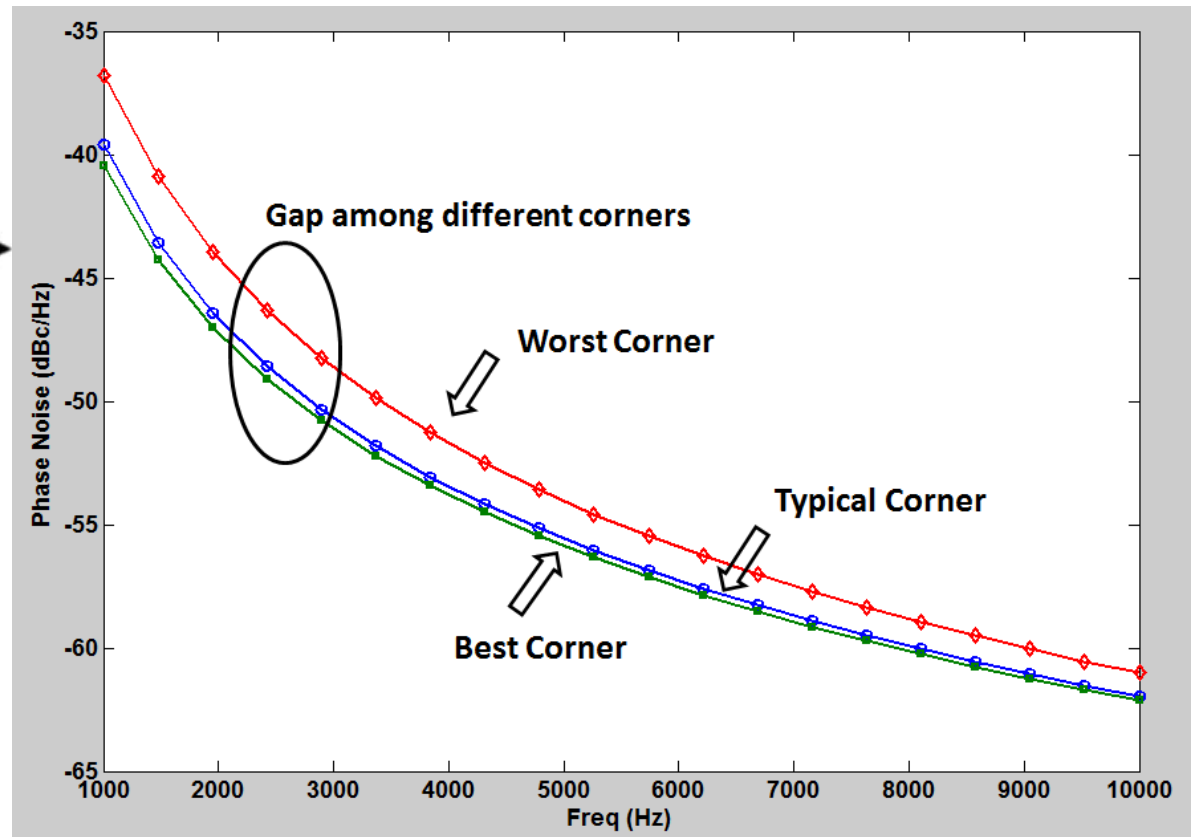
Current Solutions are expensive and slow!

Why Designers Want Noise “Corner”

- **Variation** big enough to bring **significant impact** on design.

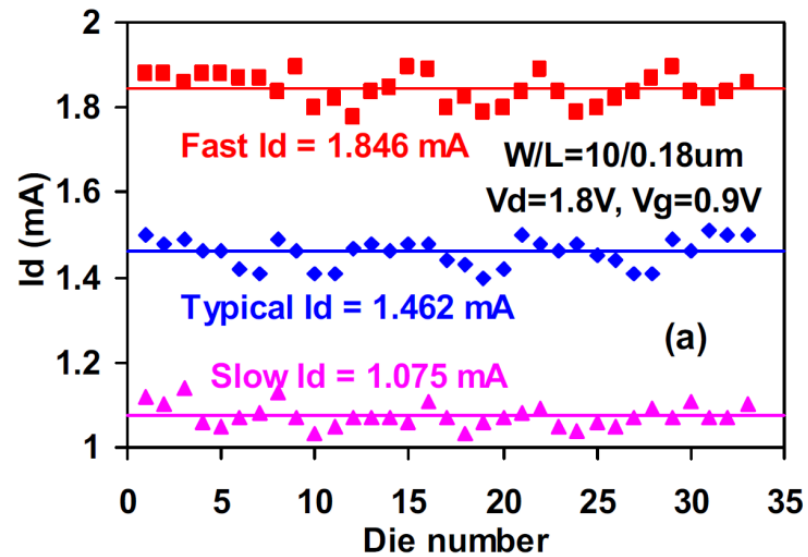
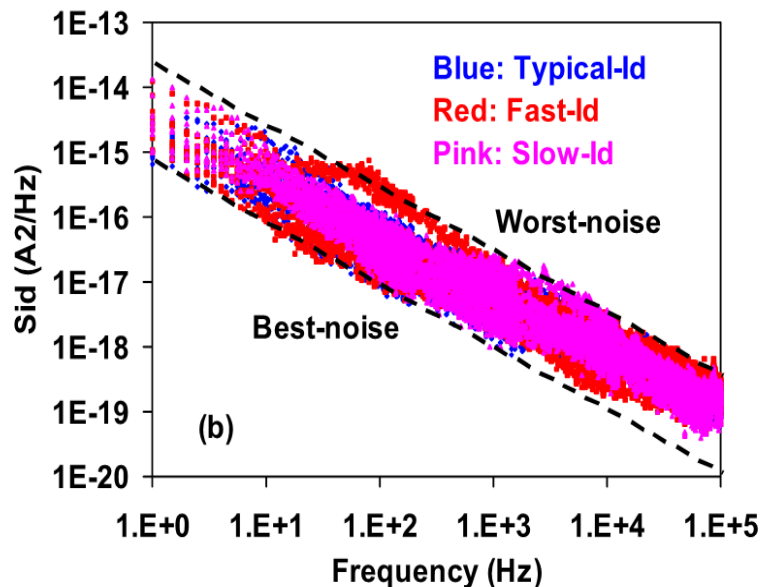


VCO Phase noise analysis with MeQLab



Noise “Corner” Key Aspects

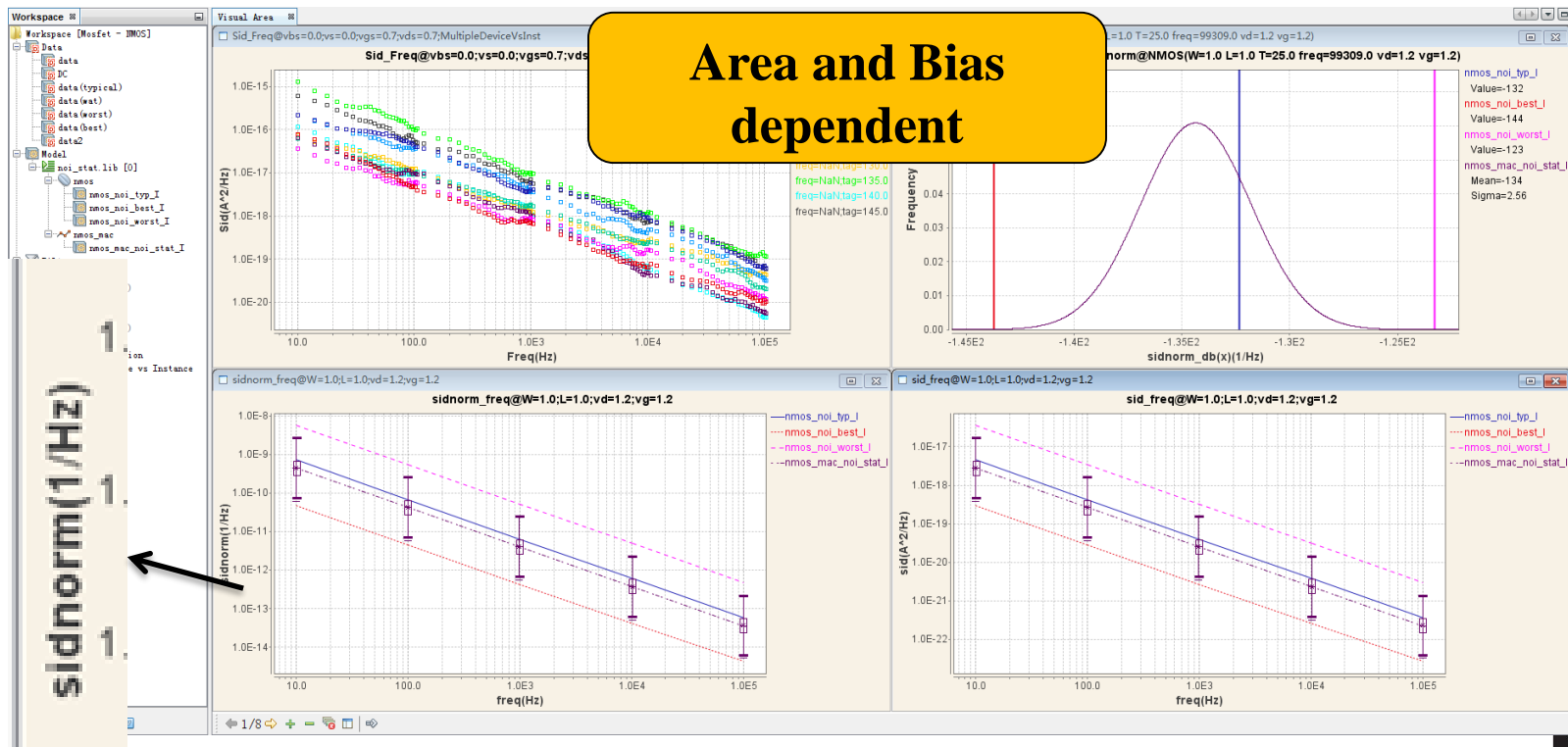
- **Sid** should be normalized by **Id**
- Variation of Sid should be **Area** dependent
 - ❖ Similar to that of mismatch
- Variation of Sid should be **Bias** dependent
 - ❖ Bigger Vg should have Less Variation



Statistical 1/f Noise Modeling with MeQLab

- Statistical noise model can be automatically generated after noise data is collected.

Statistical noise model example with MeQLab



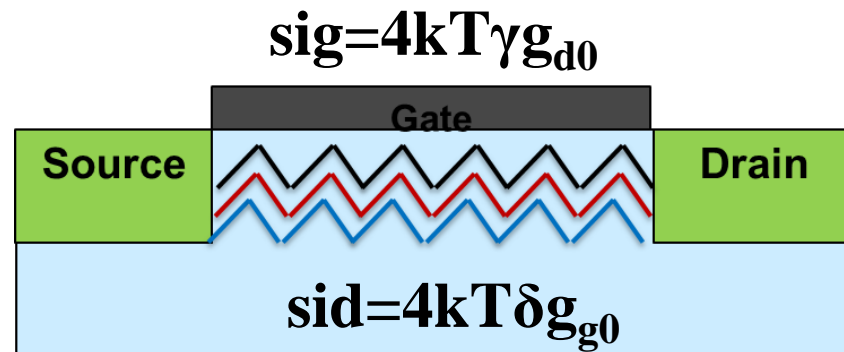
1/f Noise Summary

- Need to address noise variability for advanced nodes
 - ❖ Require **large sample** measurement
 - ❖ Require **statistical** noise modeling
 - ❖ Analog circuit require noise of **small current** (around V_t)
- Modeling Noise Corner is different from IV corner
 - ❖ Sid Normalization, area and bias dependent
- Measuring 1/f is only **half-way** through, modeling implementation and **circuit simulation** are required to complete the task

Hi Frequency Noise – Thermal Noise

- AKA white noise, independent of frequency.
- Unlike LF noise, gate noise contribute greatly at radio frequency
 - ❖ Also there is “Drain induced Gate noise”
- Currently measuring thermal noise is taking an indirect approach
 - ❖ N_{fmin} , $\Gamma(M)$, $\Gamma(P)$, R_n

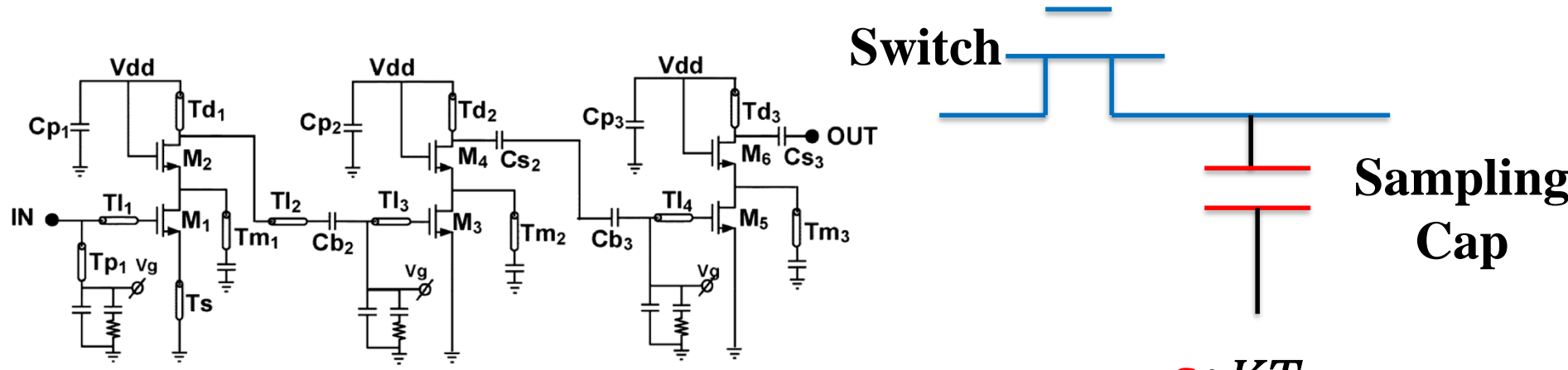
$$4kTR$$



Expensive and Unstable!

Why Designers Care about Thermal Noise

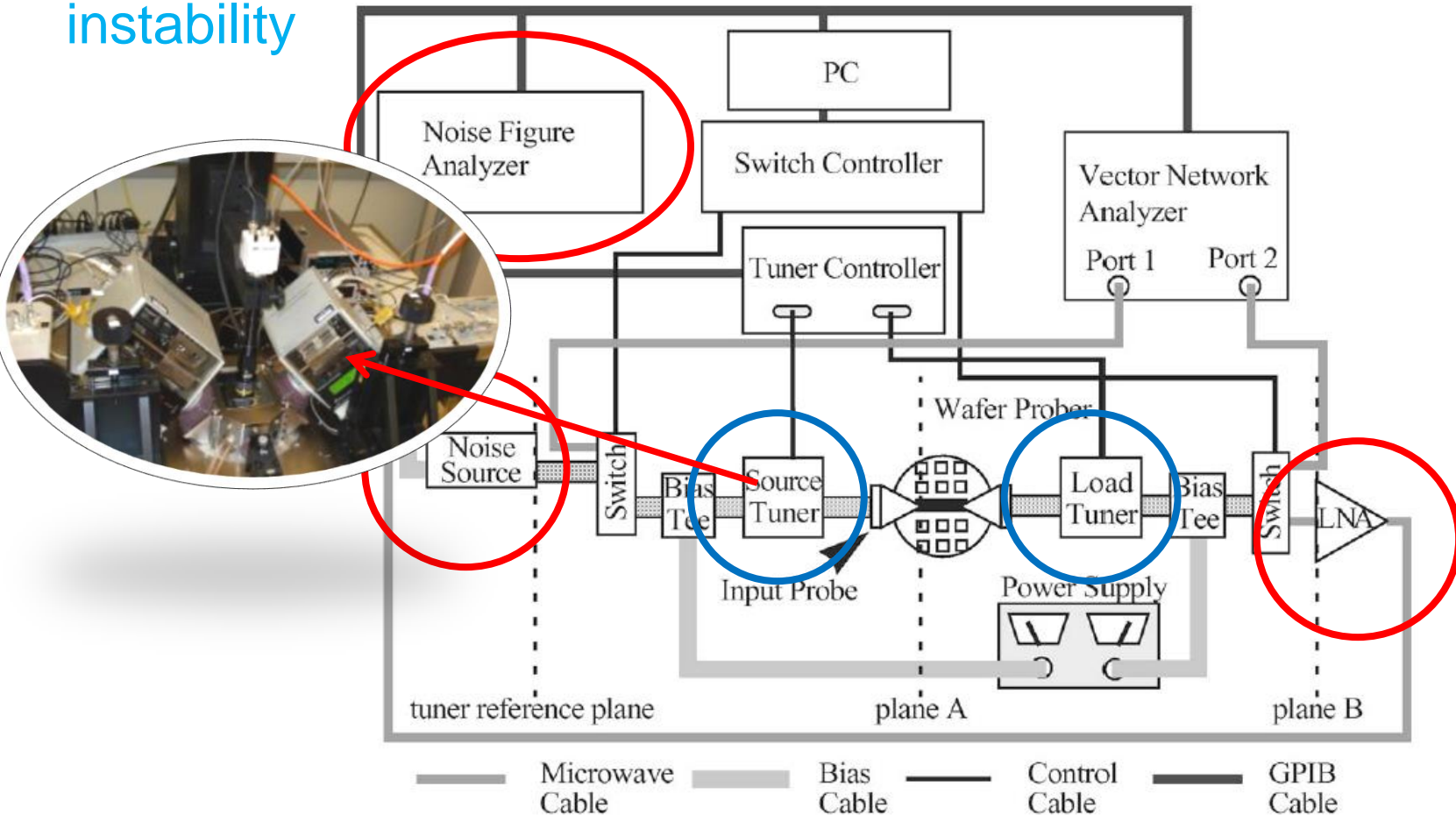
- LNA's noise figure is decided by thermal noise
- High speed, high bit ADC
 - ❖ Thermal noise decides LSB
 - ❖ User can increase switch capacitance to minimize thermal variation, however it limits the speed.



$$V^2(\text{noise_rms}) = \frac{s * KT}{C}$$

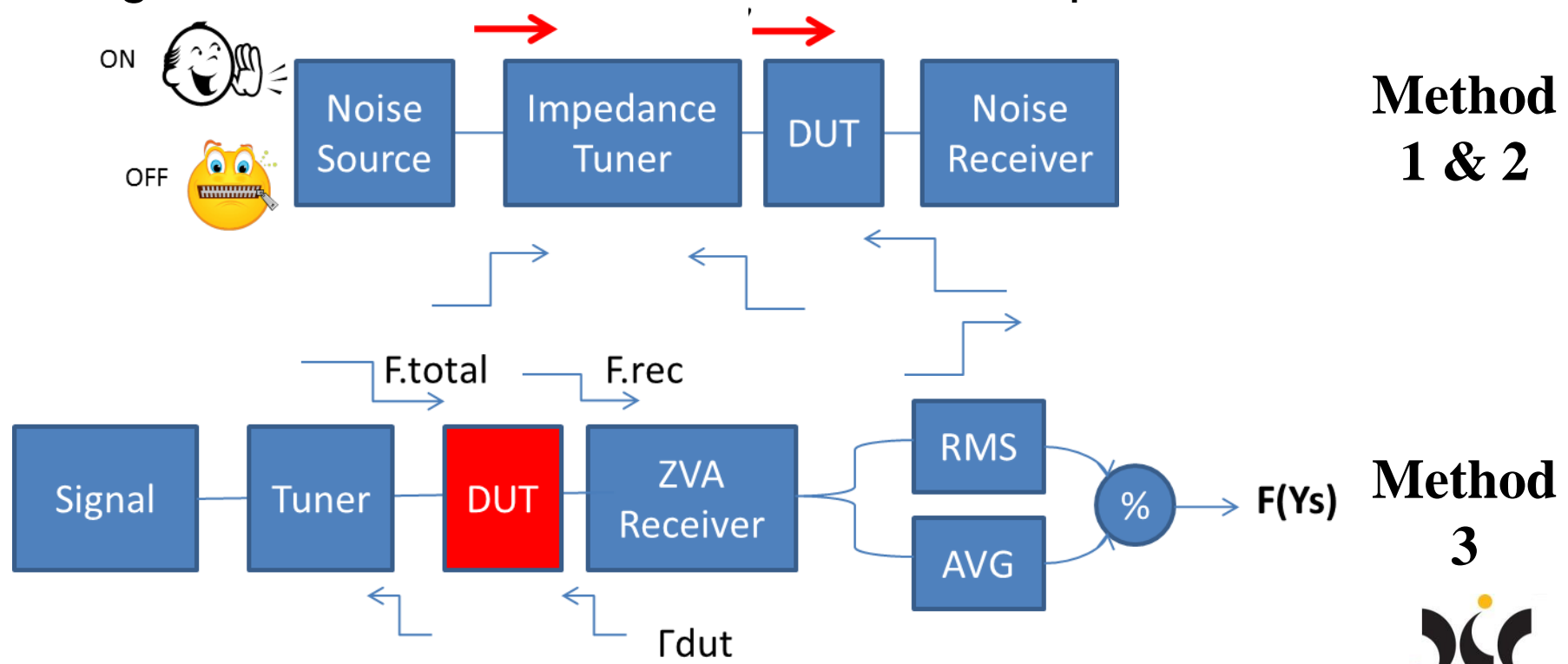
Thermal Noise Challenges

- Expensive: \$\$ and time: expensive parts and complex calibration
- Questionable results: mixed system noise and temperature instability



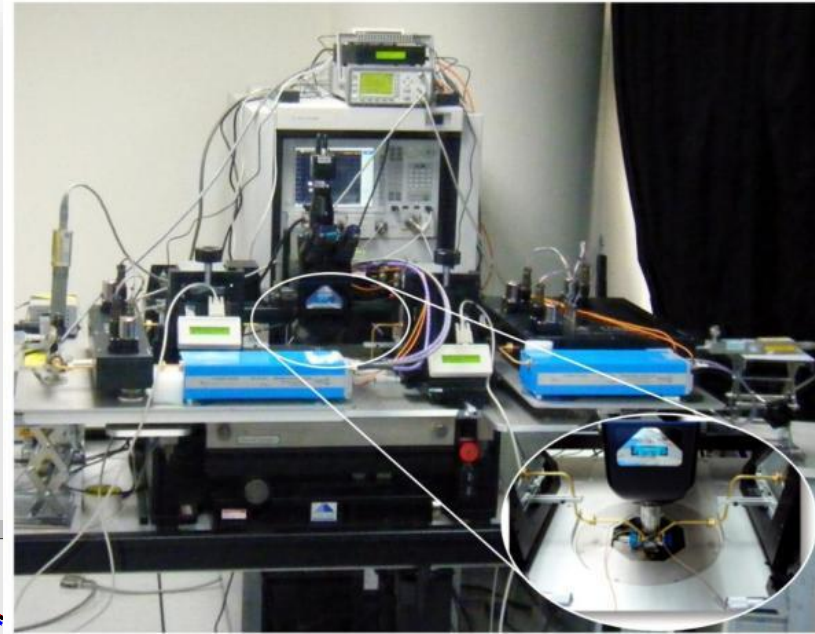
Current Thermal Noise Approaches

- 1: Compare noise output with 2 levels of source noise power
- 2: Calibrate noise receiver with noise source, rely on s-parameter to derive noise.
- 3: Signal/Noise ratio, no noise source is required

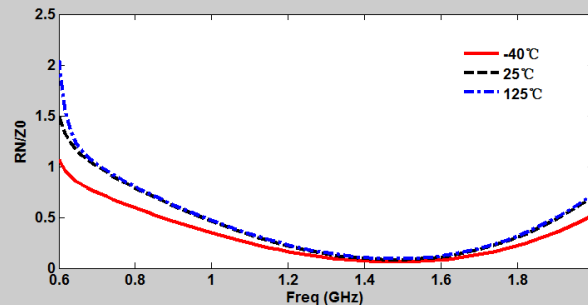
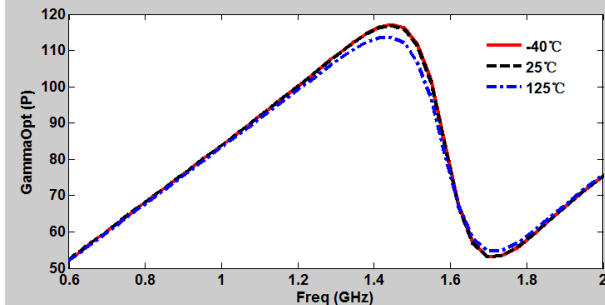
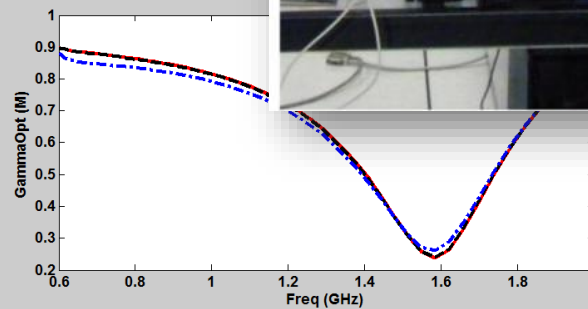
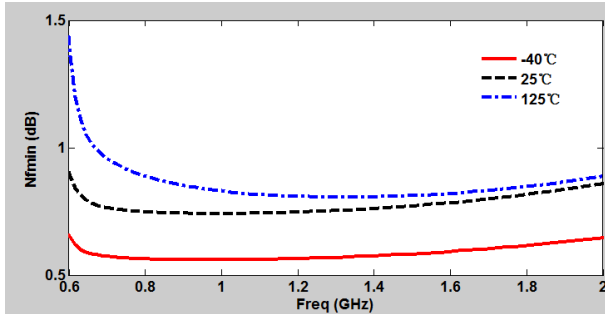


Thermal Noise: Think Outside of the Box

- Most sensitive to **Temperature** by nature
- **SPICE** is still the carrier – Text book equations
- Expensive but yet not stable
 - ❖ Remove more expensive parts such as **tuner**?



VCO Analysis with MeQLab



Thermal Noise Equations

$$R_n = \frac{S_{i_d}}{4 kT |Y_{21}|^2}$$

$$B_{\text{opt}} = -B_{\text{cor}} = \frac{S_{i_g i_d^*} \text{Re}(Y_{21})}{4 kT R_n |Y_{21}|^2} - \text{Im}(Y_{11})$$

$$G_{\text{opt}} = \left(\frac{S_{i_g}}{4 kT R_n} - |Y_{11}|^2 + 2 [\text{Re}(Y_{11}) G_{\text{cor}} + \text{Im}(Y_{11}) B_{\text{cor}}] - B_{\text{opt}}^2 \right)^{\frac{1}{2}}$$

$$F_{\text{min}} = 1 + 2R_n(G_{\text{cor}} + G_{\text{opt}})$$

$$F_{50} = F_{\text{min}} + \frac{(\frac{1}{50} - G_{\text{opt}})^2 + (-B_{\text{opt}})^2}{\frac{1}{50}} R_n.$$

For BSIM 3/4 Models

$$S_{i_d} = S_{i_d\text{-ch}} + S_{i_d\text{-sub}} + 4 kT g_m^2 R_g$$

$$S_{i_d\text{-ch}} = 4 kT \left(\frac{W}{L_{\text{eff}}} \mu_{\text{eff}} C'_{\text{ox}} \right) \times \left(\frac{V_{GT}^2 - \alpha V_{GT} V_{\text{DSeff}} + \frac{\alpha^2}{3} V_{\text{DSeff}}^2}{V_{GT} - \frac{\alpha}{2} V_{\text{DSeff}}} \right)$$

$$S_{i_g i_d^*} = S_{i_g i_d^*\text{-ch}} + S_{i_g i_d^*\text{-}R_g}$$

$$S_{i_g i_d^*\text{-}R_g} = j4 kT \omega C_{gg} g_m R_g$$

$$S_{i_g i_d^*\text{-ch}} = \frac{j4 kT \omega W^3 C'_{\text{ox}} \mu_{\text{eff}}^2}{L_{\text{eff}} I_{\text{DS}}^2} \left(\frac{1}{1 + \frac{V_{\text{DSeff}}}{E_c L_{\text{eff}}}} \right) \times \left[-\frac{1}{4} \alpha^2 V_{\text{DSeff}}^4 + \frac{\alpha}{3} (\alpha V_{as} + 2V_{GT}) V_{\text{DSeff}}^3 - \frac{V_{GT}}{2} (2\alpha V_{as} + V_{GT}) V_{\text{DSeff}}^2 + V_{GT}^2 V_{as} V_{\text{DSeff}} \right]$$

$$S_{i_g} = S_{i_g\text{-ch}} + S_{i_g\text{-}R_g}$$

$$S_{i_g\text{-}R_g} = 4 kT \omega^2 C_{gg}^2 R_g$$

$$S_{i_g\text{-ch}} = \frac{4 kT \omega^2 W^4 C'_{\text{ox}} \mu_{\text{eff}}^2}{I_{\text{DS}}^3} \left(\frac{1}{1 + \frac{V_{\text{DSeff}}}{E_c L_{\text{eff}}}} \right) \times \left[\frac{\alpha^2}{5} V_{\text{DSeff}}^5 - \frac{\alpha}{2} (\alpha V_{as} + V_{GT}) V_{\text{DSeff}}^4 + \frac{1}{3} (\alpha^2 V_{as}^2 + 4\alpha V_{GT} V_{as} + V_{GT}^2) V_{\text{DSeff}}^3 - V_{GT} V_{as} (\alpha V_{as} + V_{GT}) V_{\text{DSeff}}^2 + V_{GT}^2 V_{as}^2 V_{\text{DSeff}} \right]$$

Thermal Noise Summary

- Thermal noise greatly limits the design performance of RF and high-speed ICs
- Current thermal noise characterization systems are expensive and return questionable results.
- Stay tuned for a new thermal noise solutions.

Agenda

➤ Noise is a Source of Variability

Less Physics

➤ Noise Introduction and Its Impact on Designs

❖ RTN – SRAM

❖ 1/f – VCO

❖ Thermal - LNA

Design Perspectives

➤ PDA Noise: NC300A Introduction

❖ Reveal Architect Fundamentals

❖ Product Advances

➤ Conclusions

Measure/Simulate
Noise Accurately

Noise Characterization System Design Guidance

➤ Amplifier Design – **Smart LNA**

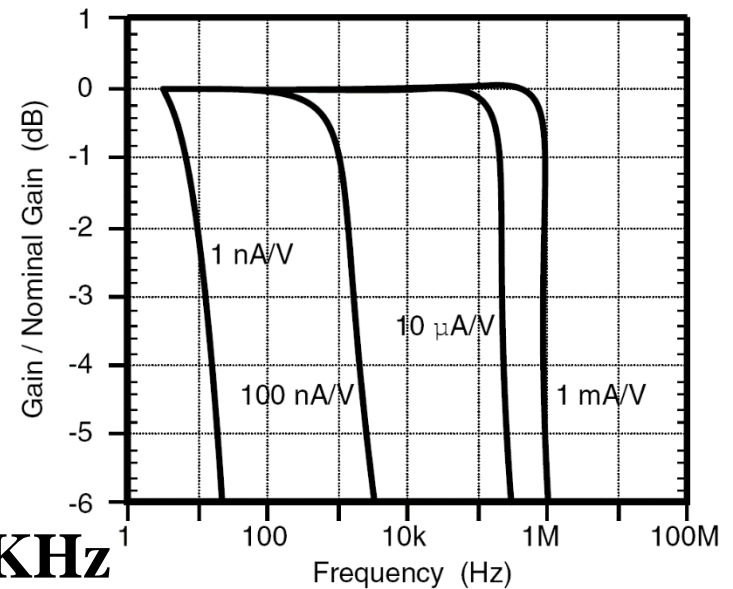
❖ Bandwidth vs. Sensitivity

❖ Roll-off $F_{\text{rolloff}} = \frac{1}{2\pi RC}$

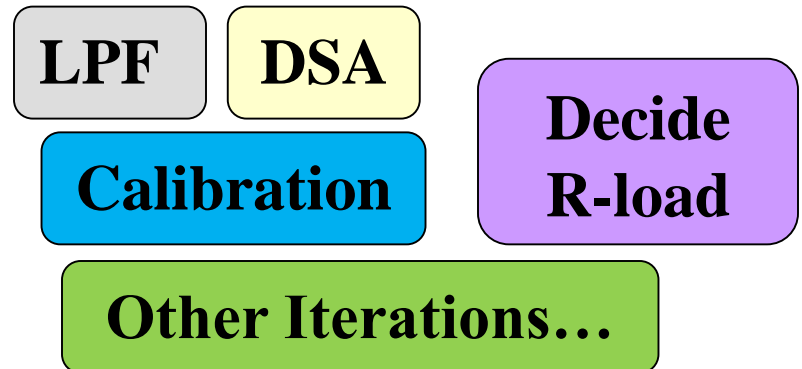
➤ “Self-adjust” Algorithm – **Plug & Play**

❖ All-in-one

➤ Remove the time-consuming piece – **Fast**



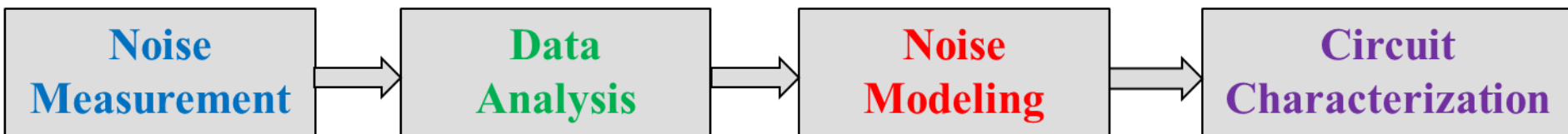
100pf, 10K, 150KHz



True Innovation is enabled by Hardware + Software

Advanced Noise Requirement Summary

- High throughput – **Fast**
- Able to measure noise of **small current**
- **Flexible** and **compact** Configuration
 - ❖ **On-Wafer** (**WAT** and **Modeling**) and **packaged part** ready
 - ❖ **Plug & Play** (Never complain customer's environment)
- **Complete**



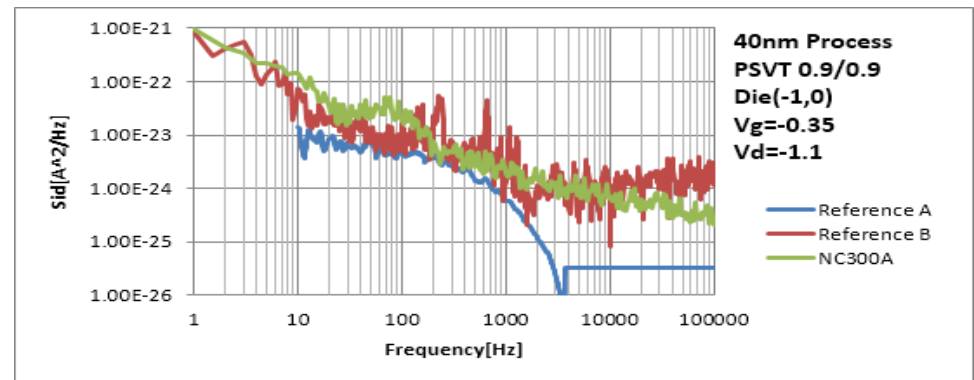
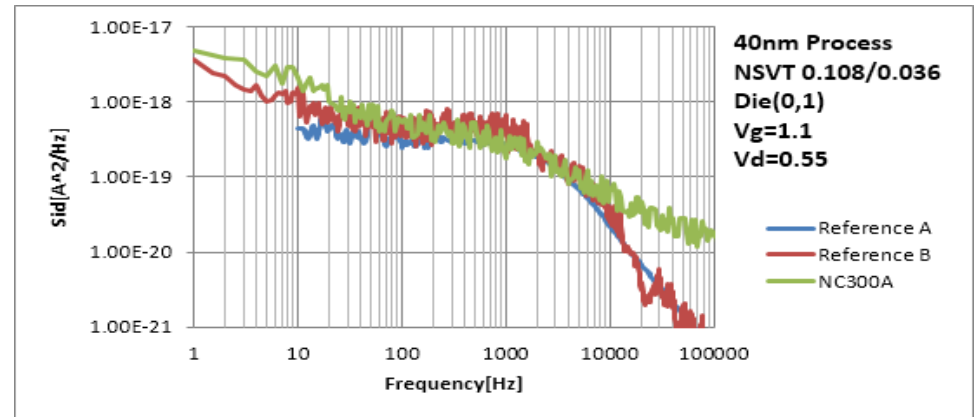
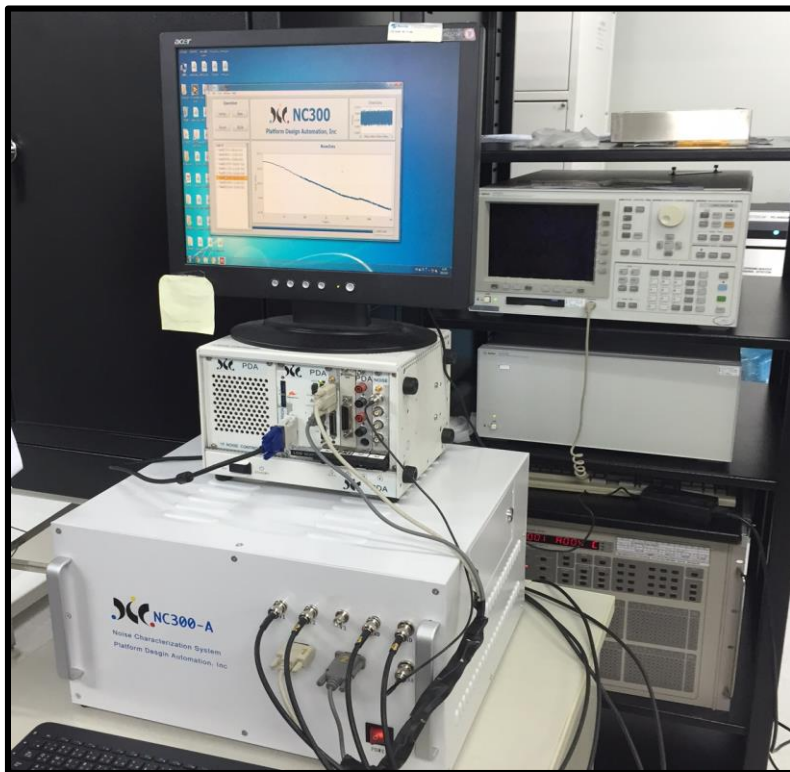
NC300A - SPEC

- 1. **Fast speed**: 10X speed up with the same accuracy
- 2. **Compact**: Integrate proprietary SMU , DSA, Smart LNA, all-in-one design
- 3. Low current noise measurement: **1pA**
- 4. **Multi-die or multi-wafer** support
- 5. **RTN** support
- 6. Lowest **System Noise Floor** (Sid): $<10^{-29}(\text{A}^2/\text{Hz})$
- 7. Noise **modeling** built-in: typical, corner and statistical
- 8. Built-in **circuit analysis** of noise impact

**Close Alliance with
National Instruments**

NC300A – Performance

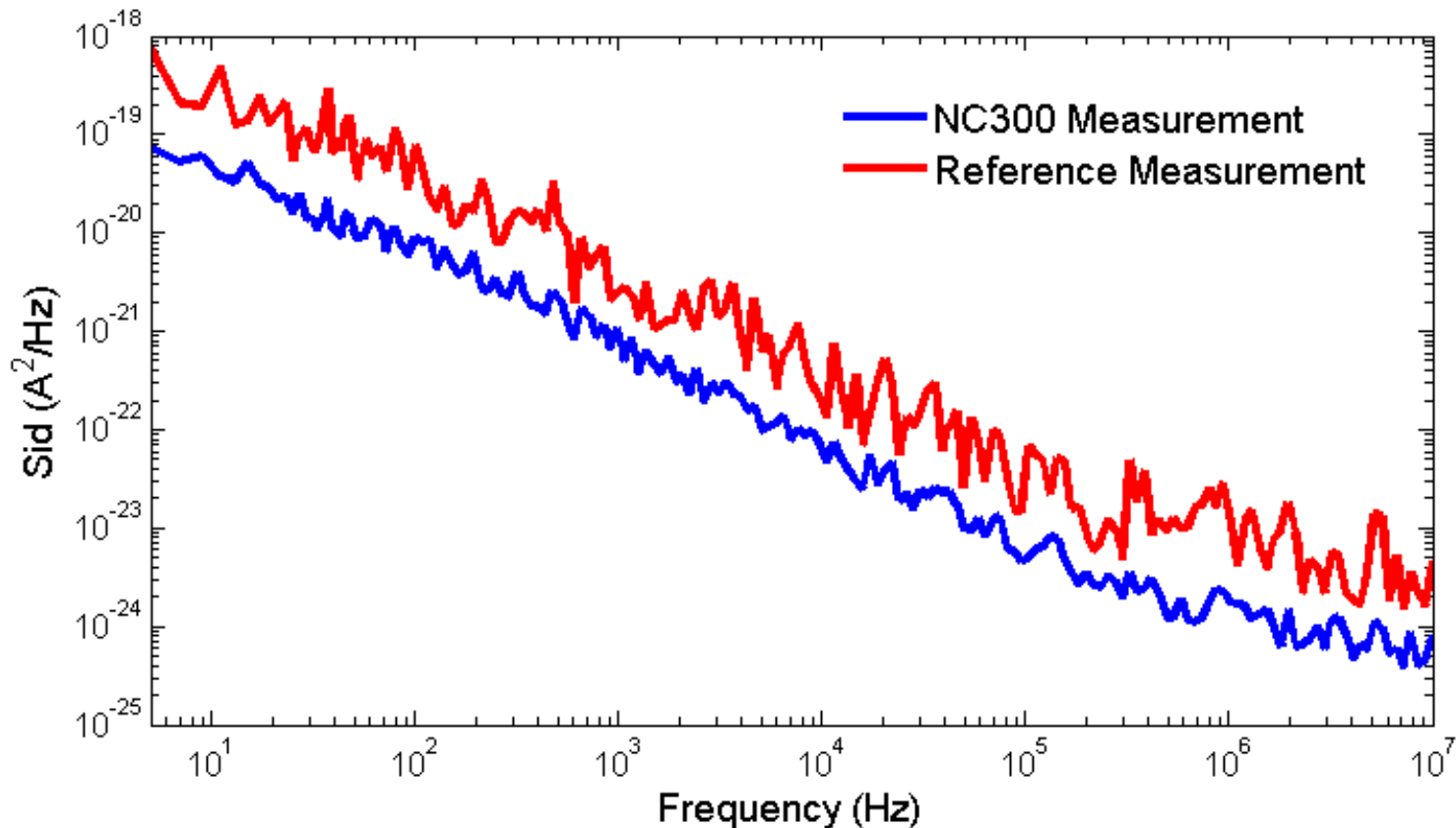
- Average measurement time for each bias: ~15 seconds
- Roll-off frequency is much higher



Competition tends to roll-off fast for small current

NC300A - Performance

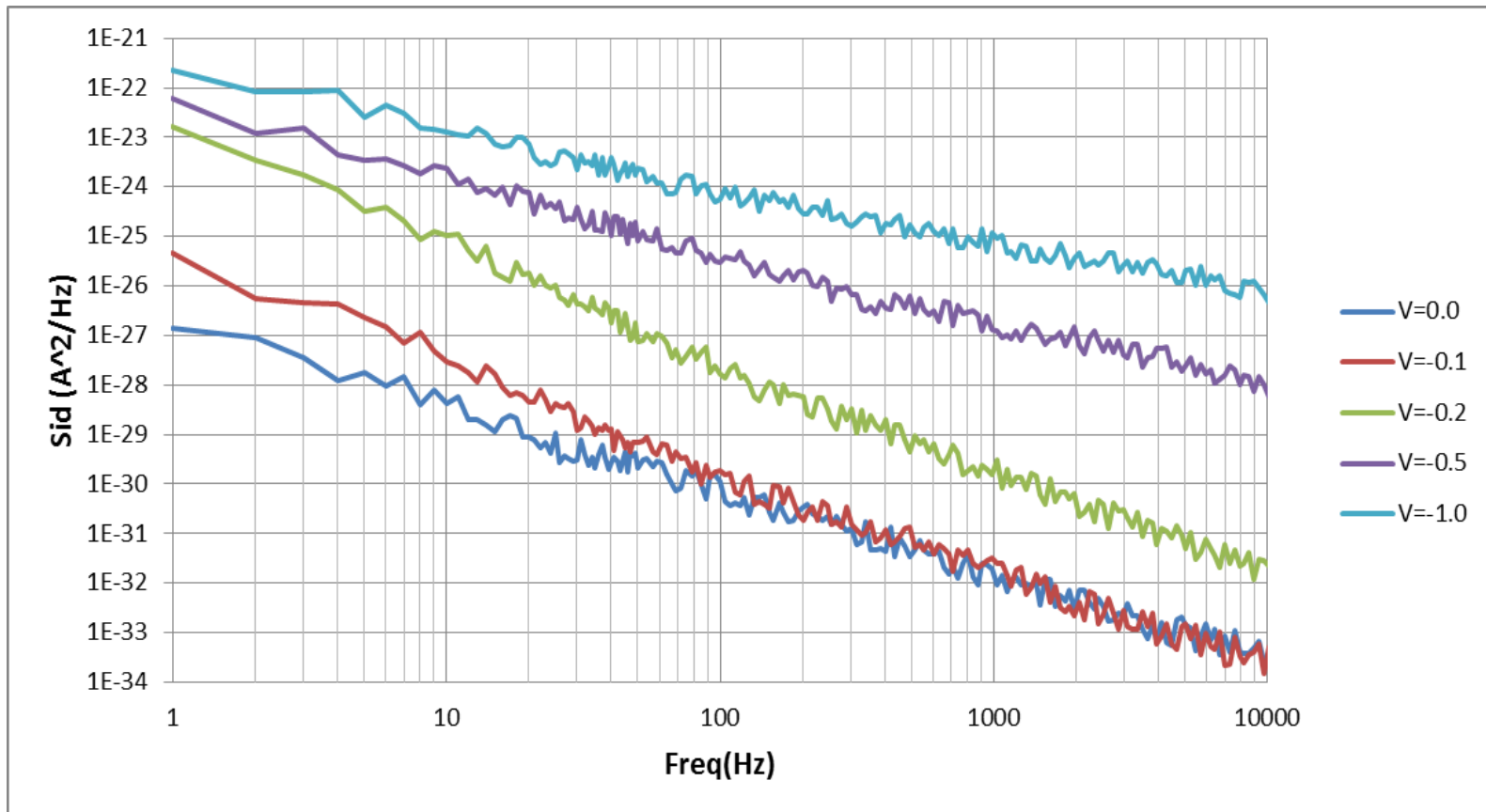
- Return true DUT current



Some system measures **higher** DUT current due to incorrect drain bias iterations

NC300A - Performance

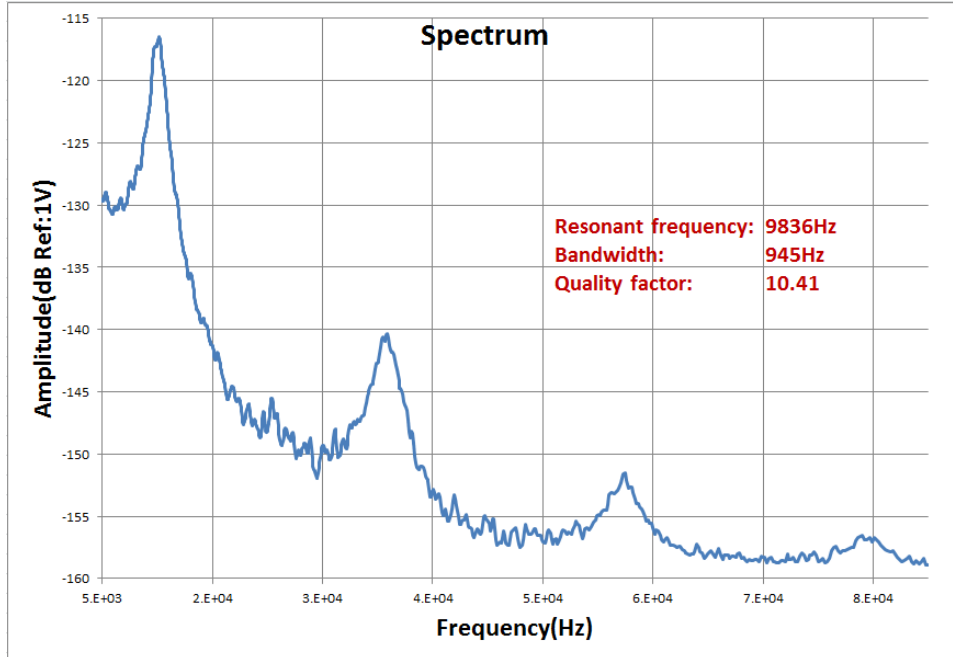
- The only system that can measure down to pA current
 - ❖ Sample shown is the noise measurement of “dark current” of a photo diode.



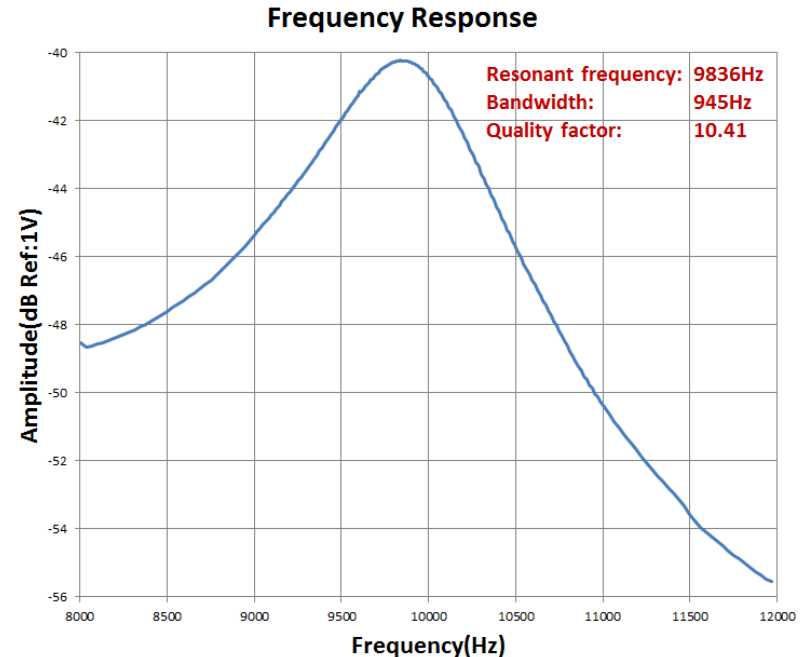
NC300A – New Applications

➤ MEMs Sensor Production Tests

- ❖ Greatly save testing time – suitable for mass production test
- ❖ Output Resonant Frequency and Quality Factor directly



Pressure Sensor Low Frequency Spectrum



Derived Quality Factor

Solution Summary

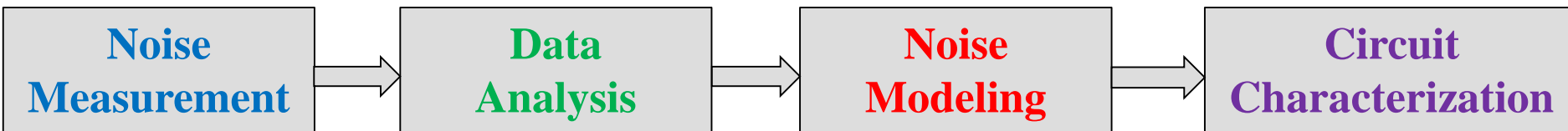
➤ Fast

- ❖ Average 15s a bias

➤ Accurate

- ❖ Lowest system noise
- ❖ High Roll-off frequency

➤ Complete



Conclusion

- Noise is an **important variability** for highly scaled designs.
- Reviewed different Noise implementation and analysis in circuit simulations.
- Low frequency noise and thermal noise characterization **insights** and **challenges**
- **NC300A** is a complete and competitive low frequency noise solution.

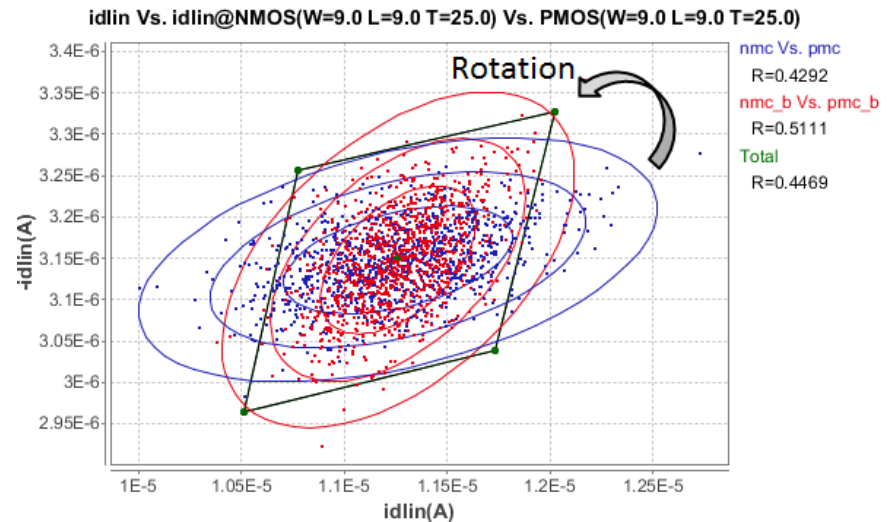
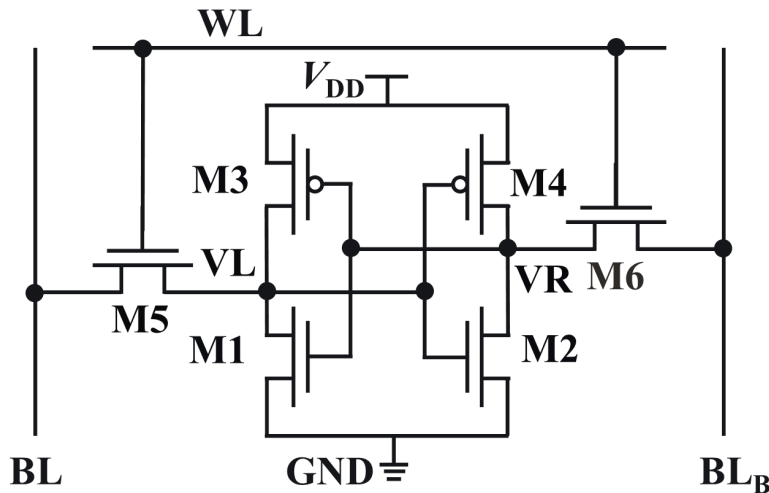
Thank you & Questions?



Platform Design Automation - The EDA Platform Company

A Machine-Learning Driven Algorithm to Achieve True Automatic Statistical and Mismatch Model Generation

<http://www.platform-da.com>



Platform Design Automation - The EDA Platform Company

RF Characterization, Modeling and Design Validation – 5G Vision and Modeling Requirements

<http://www.platform-da.com>

